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STN) & USPAT - Update
(FILE 'USPATFULL' ENTERED AT 15:41:28 ON 12 APR 2002)

L1 277 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?
L2 1509 S (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR GRIND?
L3 1765 S L1 OR L2
L4 SET HIGH OFF
476 S L3 AND (SEMICONDUCT? OR WAFER# OR CHIP#)
SET HIGH ON
L5 476 S L3 AND L4
L6 116 S L1 AND L5
L7 33 S L6 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR
L8 83 S L6 NOT L7
L9 161 S L1 NOT (L7 OR L8)
L10 6 S L9 AND (CMP OR POLISH? OR CHEMIMECH? OR PLANARIZ? OR LAP? OR
L11 155 S L9 NOT L10
SET HIGH OFF
L12 365 S L2 AND (SEMICONDUCT? OR WAFER# OR CHIP#)
SET HIGH ON
L13 365 S L2 AND L12
L14 360 S L13 NOT L1
SET HIGH OFF
L15 2 S L14 AND MASS?(3A)SPEC?
SET HIGH ON
L16 2 S L14 AND L15

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